

FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- Low forward voltage drop, High current capability
- Soft recovery improves EMC performance
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015\863\EU

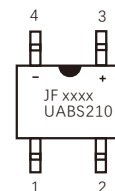
MECHANICAL DATA

- Case:ABS molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750,method 2026
- Mounting Position: Any

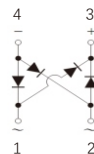
TYPICAL APPLICATIONS

Used in AC/DC bridge full wave rectification for SMPS, lighting ballaster, adapter, charger, home appliances, office equipment, and telecommunication applications.

ABS



Pin Diagram



Internal Schematic

Marking
JF:Logo
XXXX:Data code
UABS210:Type

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating at 25°C ambient temperature unless otherwise specified. Single phase ,half wave ,60Hz,resistive or inductive load. For capacitive load,derate current by 20%.)

Parameters		Symbols	Value	Units
Maximum Recurrent Peak Reverse Voltage		V_{RRM}	1000	Volts
Maximum RMS Voltage		V_{RMS}	700	Volts
Maximum DC Blocking Voltage		V_{DC}	1000	Volts
Maximum Average Forward Rectified Current		$I_{(AV)}$	2.0	Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		I_{FSM}	50	Amps
Rating for fusing (t=8.3ms)		I^2t	10.735	A ² s
Maximum DC Reverse Current at rated DC blocking voltage	T _A =25°C	I_R	5	μA
	T _A =125°C		100	
Maximum Instantaneous Forward Voltage at 2.0A		V_F	1.7	Volts
Typical thermal resistance(Note2)		$R_{\theta JA}$	62.5	°C/W
		$R_{\theta JL}$	25	
Maximum reverse recovery time(Note1)		t_{rr}	75	ns
Operating junction and storage temperature range		T _J T _{STG}	-55 to +150	°C

Note: 1.Test conditions: IF=0.5A,IR=1.0A,IRR=0.25A.

2.Device mounted on FR-4 substrate, 1"×1", 2oz, single-sided, PC boards with 0.56"×0.73" copper pad.

AVAILABLE PACK INFORMATION

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Quantity (reel/box)	Quantity (box/carton)	Quantity (K/carton)
UABS210-ABS	T/R	Φ330	3000	2	8	48

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

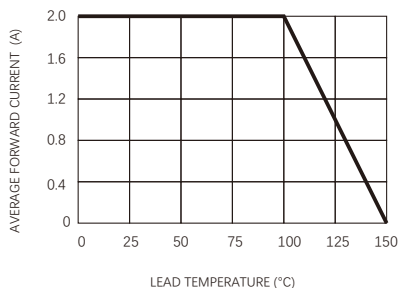


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

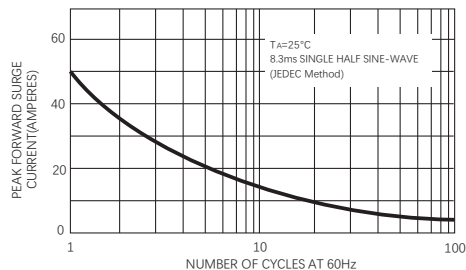


FIG4-TYPICAL FORWARD CHARACTERISTICS

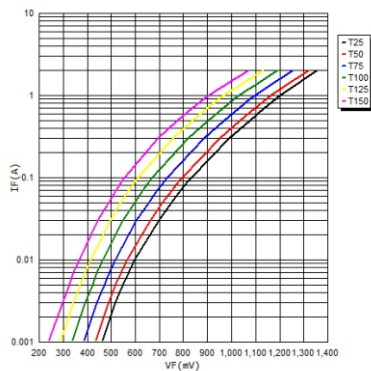


FIG.3-TYPICAL REVERSE CHARACTERISTICS

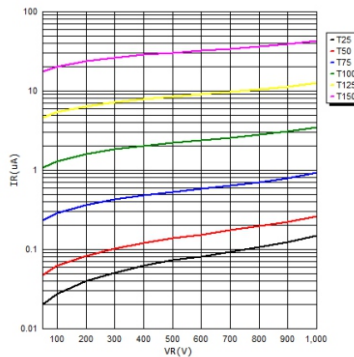
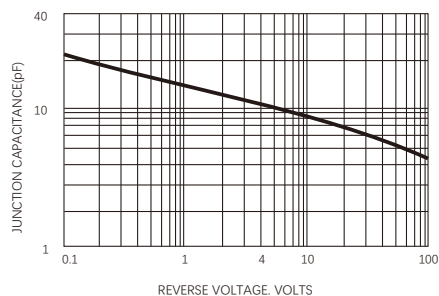
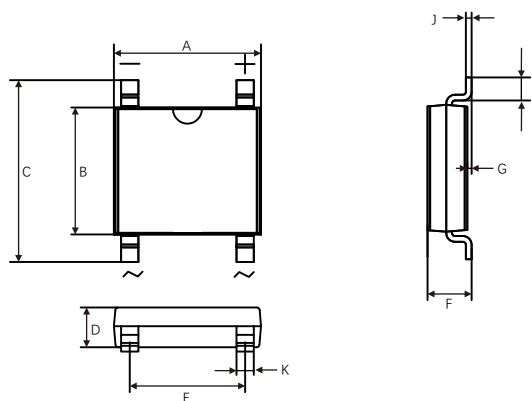


FIG.5-TYPICAL JUNCTION CAPACITANCE



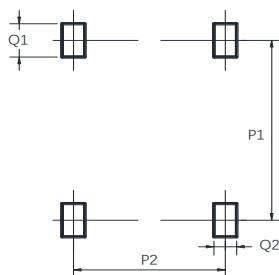
PACKAGE OUTLINE DIMENSIONS

ABS



UNIT:mm		
DIM	MIN	MAX
A	4.80	5.40
B	4.20	4.60
C	6.00	6.80
D	1.20	1.50
E	3.80	4.40
F	1.22	1.60
G	0.05	0.15
I	0.30	0.80
J	0.10	0.30
K	0.50	0.85

Suggested solder pad layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90

Dimensions in millimeters

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